

**HOSTAFORM® M10AE**

POM

Celanese

Processing/Physical Characteristics	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melt volume-flow rate, MVR	<b>0.9</b>	cm <sup>3</sup> /10min	ISO 1133
Temperature	<b>190</b>	°C	-
Load	<b>2.16</b>	kg	-

[C]: CAMPUS

Mechanical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	<b>2800</b>	MPa	ISO 527
<sup>[C]</sup> Yield stress	<b>65</b>	MPa	ISO 527
<sup>[C]</sup> Yield strain	<b>9</b>	%	ISO 527
<sup>[C]</sup> Nominal strain at break	<b>25</b>	%	ISO 527
<sup>[C]</sup> Charpy impact strength, +23°C	<b>220</b>	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy impact strength, -30°C	<b>200</b>	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	<b>10</b>	kJ/m <sup>2</sup>	ISO 179/1eA
<sup>[C]</sup> Charpy notched impact strength, -30°C	<b>8</b>	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

Thermal properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melting temperature, 10°C/min	<b>167</b>	°C	ISO 11357-1/-3
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	<b>97</b>	°C	ISO 75-1/-2
<sup>[C]</sup> Coeff. of linear therm. expansion, parallel	<b>130</b>	E-6/K	ISO 11359-1/-2

[C]: CAMPUS

Electrical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Relative permittivity, 100Hz	<b>4</b>	-	IEC 62631-2-1
<sup>[C]</sup> Relative permittivity, 1MHz	<b>4</b>	-	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 100Hz	<b>20</b>	E-4	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 1MHz	<b>50</b>	E-4	IEC 62631-2-1
<sup>[C]</sup> Volume resistivity	<b>1E12</b>	Ohm*m	IEC 62631-3-1
<sup>[C]</sup> Surface resistivity	<b>1E14</b>	Ohm	IEC 62631-3-2
<sup>[C]</sup> Electric strength	<b>28</b>	kV/mm	IEC 60243-1

[C]: CAMPUS

Other properties	Value	Unit	Test Standard
<sup>[C]</sup> Water absorption	<b>0.65</b>	%	Sim. to ISO 62
<sup>[C]</sup> Humidity absorption	<b>0.2</b>	%	Sim. to ISO 62
<sup>[C]</sup> Density	<b>1410</b>	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

**Characteristics****Processing**

Injection Molding, Film Extrusion, Profile Extrusion, Sheet Extrusion, Other Extrusion, Blow Molding

**Delivery form**

Pellets

**Additives**

Release agent

**Features**

Copolymer

**Regional Availability**

North America, Europe, Asia Pacific, South and Central America, Near East/Africa

**Other text information****Film extrusion**

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C  
Annealing time 10 min/mm thickness

**Other extrusion**

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C  
Annealing time 10 min/mm thickness

**Profile extrusion**

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C  
Annealing time 10 min/mm thickness

### Sheet extrusion

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C  
Annealing time 10 min/mm thickness

### Blow molding

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Standard extruders with plasticating screws (20 to 25 D) will fit.

Melt temperature 180-190 °C  
Mould-surface temperature 60-100 °C

Conditioning e.g. moisturizing is not necessary.